

Remarks

Reconsideration of this patent application is respectfully requested, particularly as herein amended.

Before turning to the merits of the Office Action of August 10, 2005, the undersigned would like to thank the Examiner for the thorough and extensive interview which was conducted on December 20, 2005. These discussions were helpful in framing the issues presented in this matter, and the present Reply is being filed in furtherance of these discussions.

Turning next to the Office Action of August 10, 2005, a single issue is presented, namely, a rejection of applicant's claims 1 to 12 under 35 U.S.C. §103(a) as being unpatentable over a combination of patents including Feygin (US 4,752,352) and Kinzie (US 5,015,312).

As noted at the interview, however, neither Feygin nor Kinzie discloses the building up of a plurality of unitary laminations to form an assembly of the unitary laminations, and the clamping of the assembly of the unitary laminations together to form a self-supporting structure, as disclosed in the first sentence of paragraph [0008] of applicant's specification and as is presently recited in applicant's claims.

In Feygin, each lamination 24 is "spot brazed" or "bonded" to the assembly which is being developed in the stack holder 74 of the assembly station 38, "integrally bonding each of

the individually contoured laminations 24 to the next adjacent of the individually contoured laminations 24 to complete the formation of the three-dimensional object 22 (see, for example, column 6, lines 46 to 59).

In Kinzie, an "adhesive" is applied "over each profile as well as the area inside each profile for use in laminating the profiles together", before any of the profiles are cut away from the sheet material 27 (see, column 8, lines 6 to 35), and each planar element is later "pressed" by a roller 143 "to complete the bonding of the planar element so formed to the planar element directly underneath it" (see, column 12, lines 4 to 8).

Consequently, in each case, some form of bonding is used to join the various layers of the assembly, which is to be distinguished from the clamping of the unitary laminations which is recited in applicant's claims. Moreover, in each case, the various layers are bonded to one another, layer by layer, which is to be distinguished from applicant's assembly of the unitary laminations, which are not bonded to one another, layer by layer, but which are instead clamped together upon assembly.

Accordingly, it is submitted that applicant's claims 1 to 12 would not have been obvious to the person of ordinary skill at the time the present invention was made in view of the teachings of Feygin and Kinzie because there would have been no motivation to clamp together assemblies which had already been joined together by bonding.

In view of the foregoing, it is submitted that the

present application is in condition for allowance. In the event that any additional issues are identified which will require further consideration, the Examiner is invited to telephone the undersigned to discuss and resolve such issues.

Applicant further encloses an "Information Disclosure Statement" which is being submitted to inform the Patent Office of information cited in an Office Action which has recently been issued by the U.S. Patent Office in one of the applications which had previously been noted in applicant's Information Disclosure Statement filed July 19, 2004, and to inform the Patent Office of two other patent applications which had recently entered the U.S. national stage and the foreign Search Reports related to the International Applications from which these U.S. patent applications derived. Corresponding action is earnestly solicited.

Also enclosed with this Information Disclosure Statement is a signed "Power of Attorney" for this patent application. Entry of the enclosed Power of Attorney is respectfully requested.

Respectfully submitted,



GARY M. COHEN, ESQ.
Reg. No. 28,834
Attorney for Applicant
Tel.: (610) 975-4430